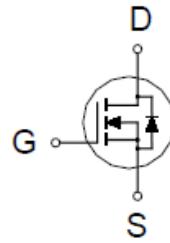
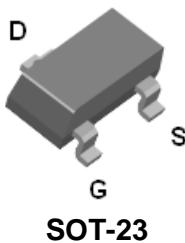


PB210BM

N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
100V	230mΩ @ $V_{GS} = 10V$	1.3A



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $T_A = 25^\circ C$	I_D	1.3	A
$T_A = 100^\circ C$	I_D	0.8	
Pulsed Drain Current ¹	I_{DM}	18	
Avalanche Current	I_{AS}	18	
Avalanche Energy	E_{AS}	16.5	mJ
Power Dissipation $T_A = 25^\circ C$	P_D	0.75	W
$T_A = 70^\circ C$	P_D	0.3	
Operating Junction & Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$		166	°C / W
Junction-to-Case	$R_{\theta JC}$		60	

¹Pulse width limited by maximum junction temperature.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

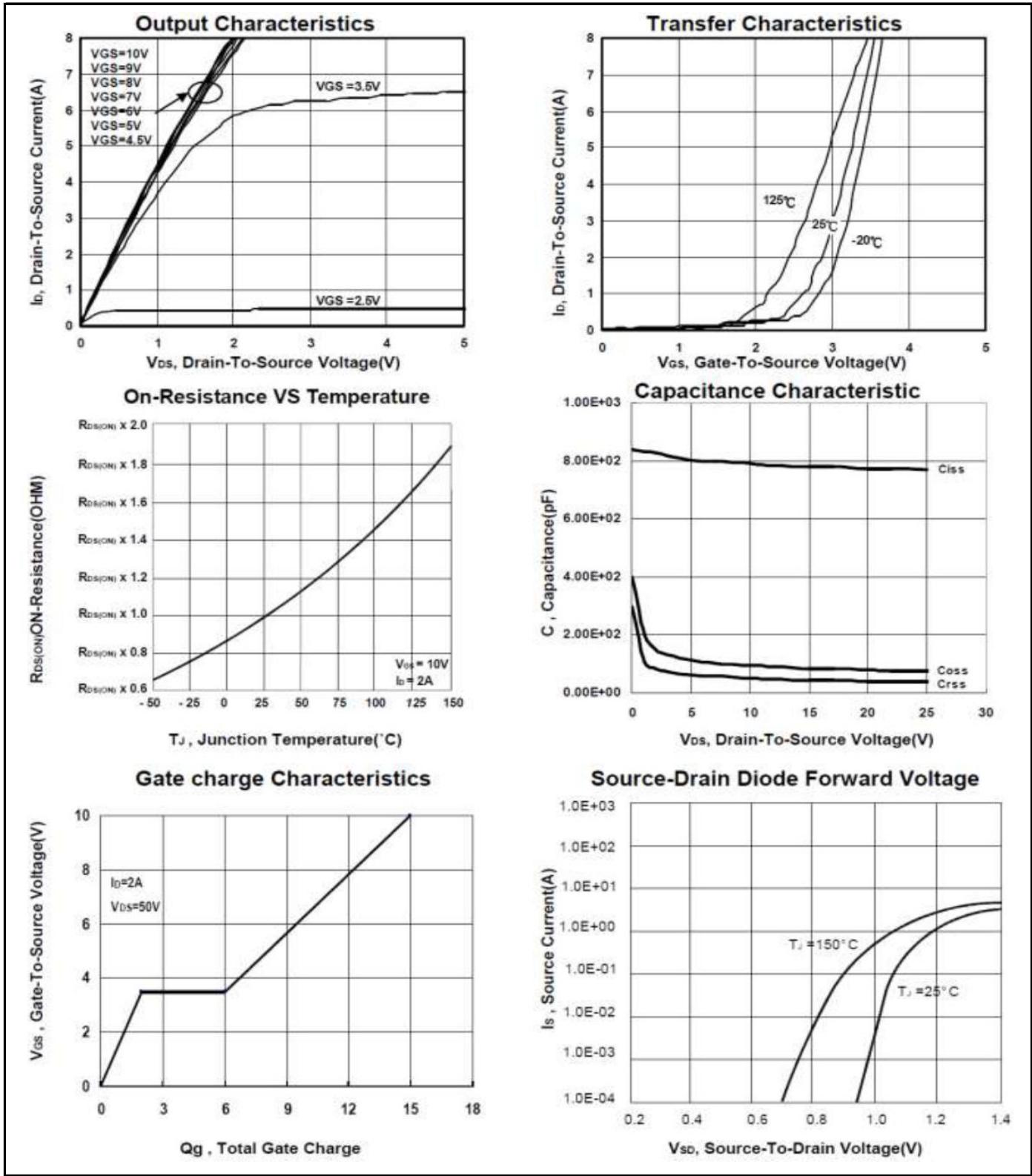
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	1.5	2	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 80\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 80\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 10\text{V}$	18			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_D = 2\text{A}$		220	230	$\text{m}\Omega$
		$V_{\text{GS}} = 5\text{V}, I_D = 1\text{A}$		230	240	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 10\text{V}, I_D = 2\text{A}$		10		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$		802		pF
Output Capacitance	C_{oss}			80		
Reverse Transfer Capacitance	C_{rss}			41		
Gate Resistance	R_g	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		2.5		Ω
Total Gate Charge ²	Q_g	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 2\text{A}$		15		nC
Gate-Source Charge ²	Q_{gs}			2		
Gate-Drain Charge ²	Q_{gd}			4		
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 50\text{V}, I_D \approx 2\text{A}, V_{\text{GEN}} = 10\text{V}, R_{\text{GS}} = 6\Omega$		16		nS
Rise Time ²	t_r			330		
Turn-Off Delay Time ²	$t_{\text{d}(\text{off})}$			39		
Fall Time ²	t_f			111		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current	I_S				10	A
Forward Voltage ¹	V_{SD}	$I_F = 2\text{A}, V_{\text{GS}} = 0\text{V}$			1.4	V
Reverse Recovery Time	t_{rr}	$I_F = 2\text{A}, dI/dt = 500\text{A}/\mu\text{s}$		75		nS
Reverse Recovery Charge	Q_{rr}			0.17		nC

¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

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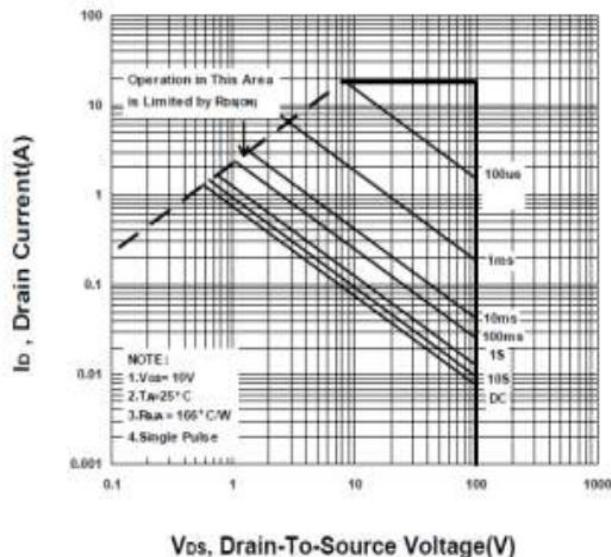
N-Channel Enhancement Mode MOSFET



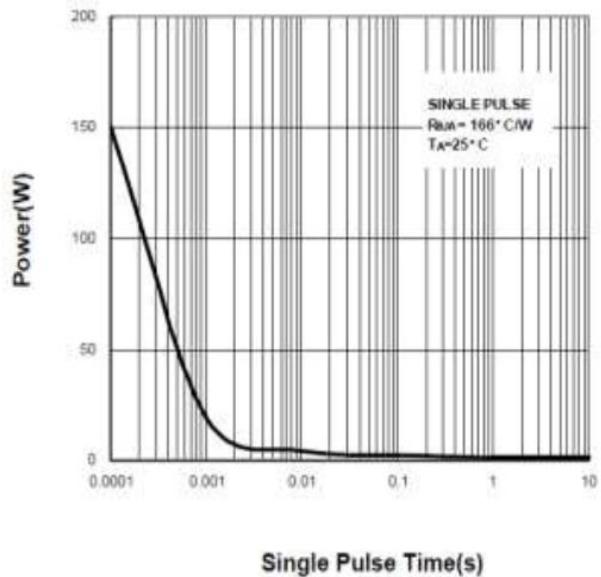
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N-Channel Enhancement Mode MOSFET

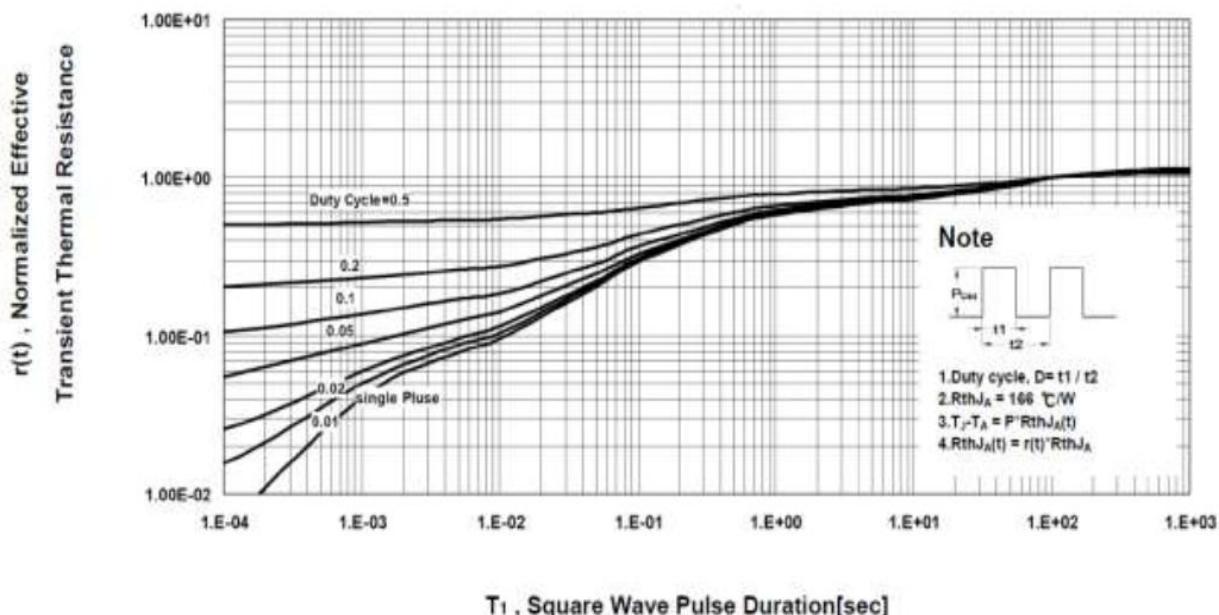
Safe Operating Area



Single Pulse Maximum Power Dissipation

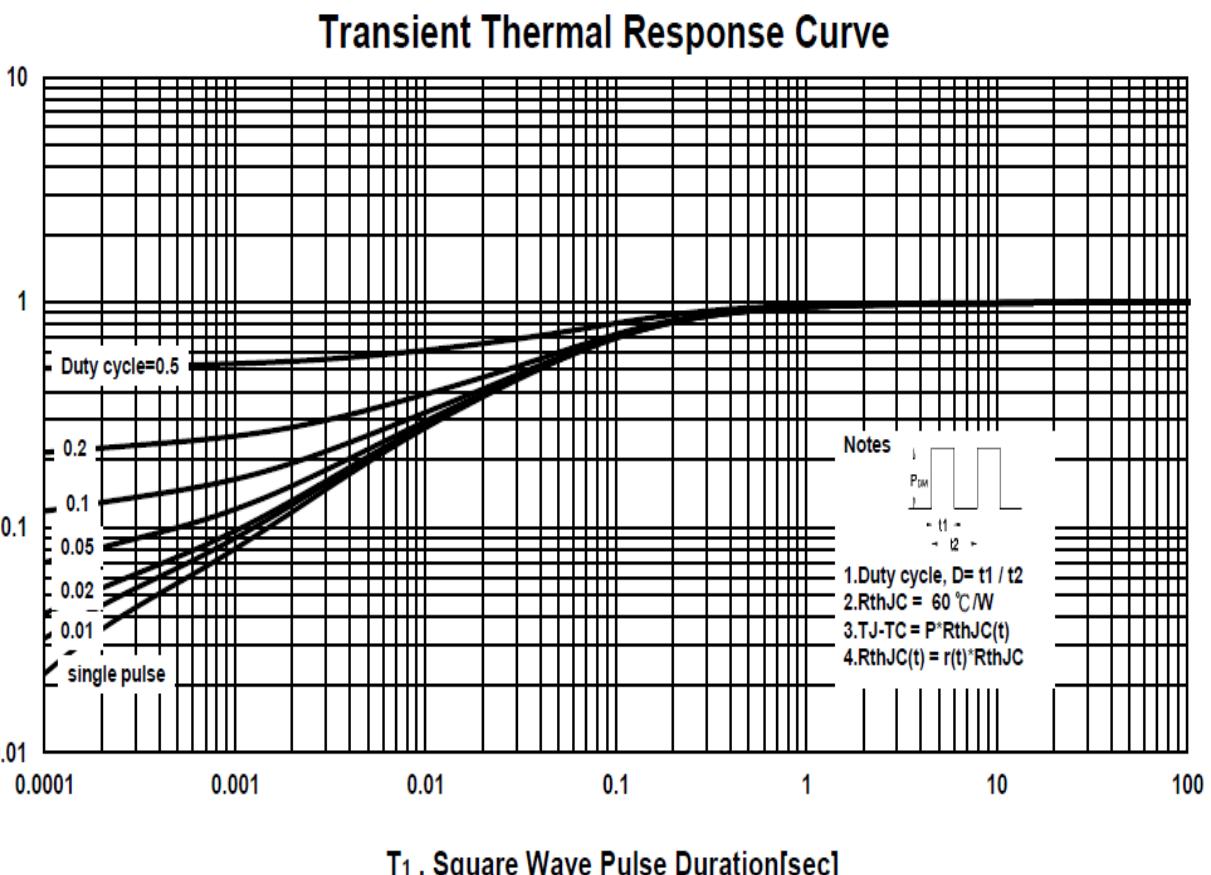


Transient Thermal Response Curve



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N-Channel Enhancement Mode MOSFET



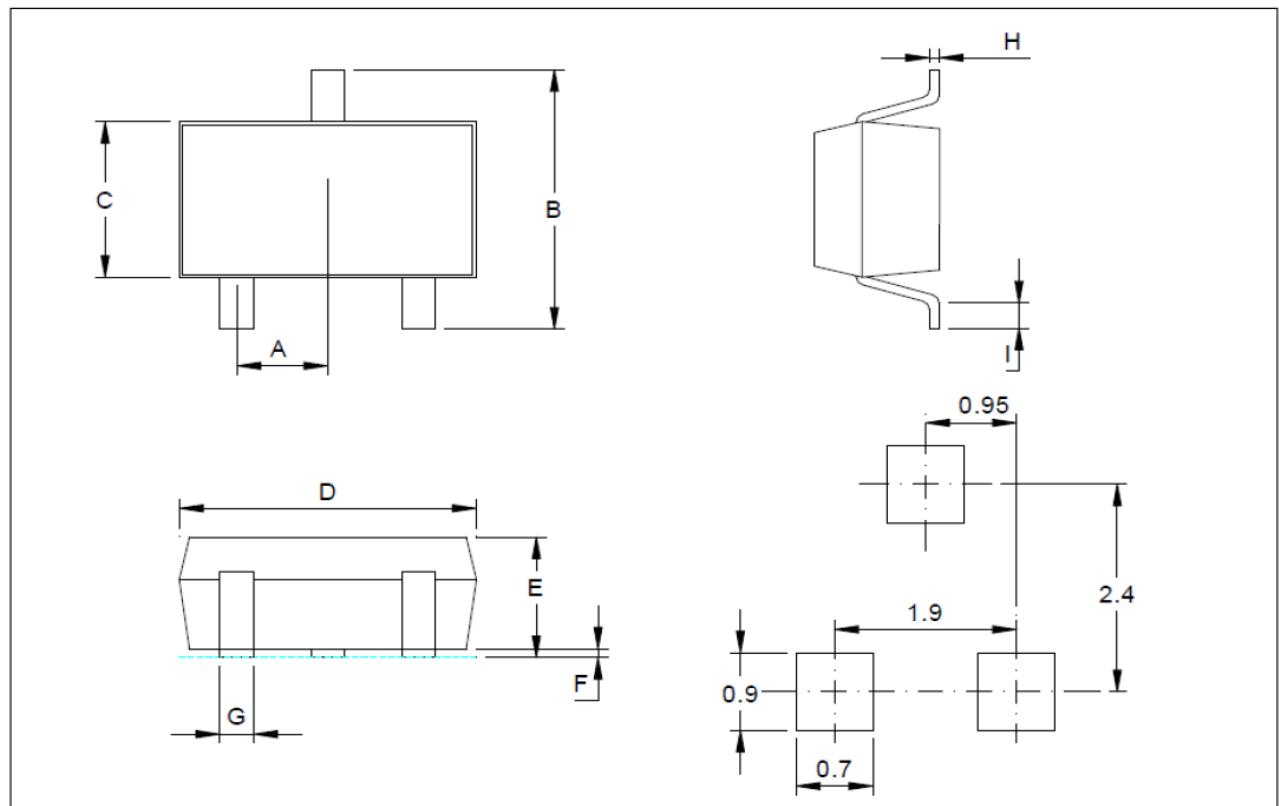
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N-Channel Enhancement Mode MOSFET

Package Dimension

SOT-23 MECHANICAL DATA

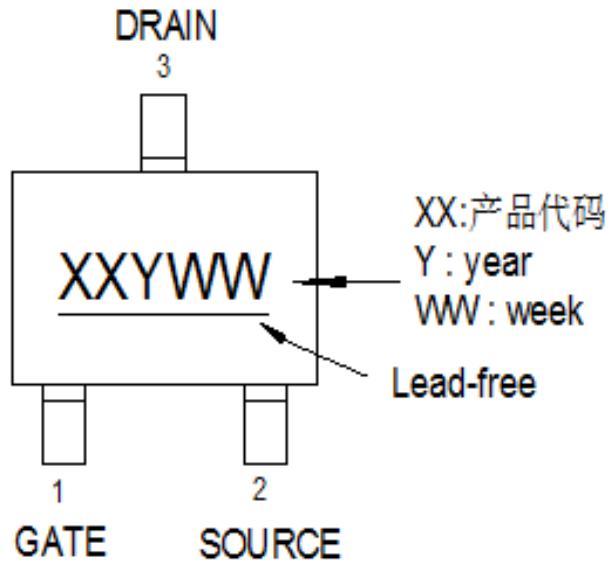
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A		1.05		H	0.1		0.2
B	2.4		3	I	0.3		0.6
C	1.4		1.73				
D	2.7		3.1				
E	1		1.31				
F	0		0.15				
G	0.3		0.5				



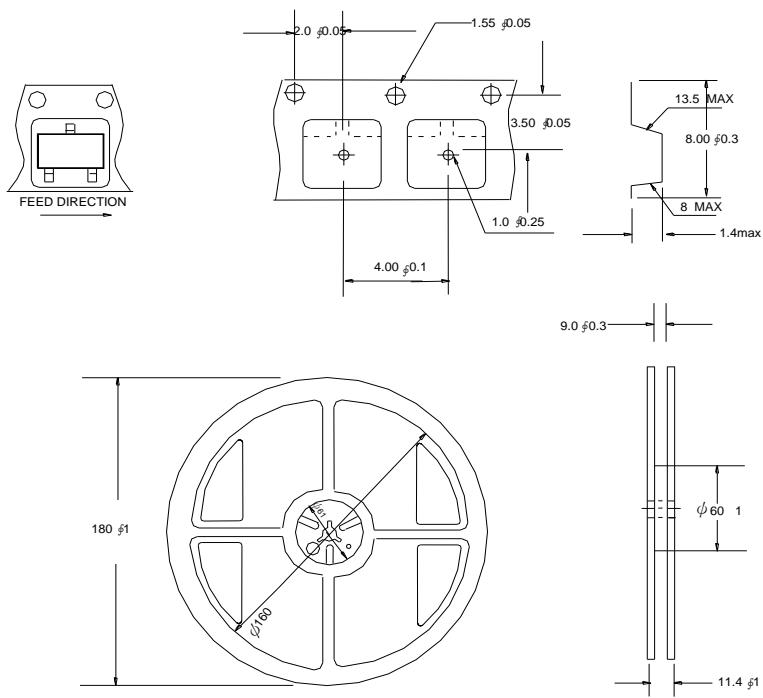
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N-Channel Enhancement Mode MOSFET

A. Marking Information (此产品代码为：1V)



B. Tape&Reel Information: 3000pcs/Reel

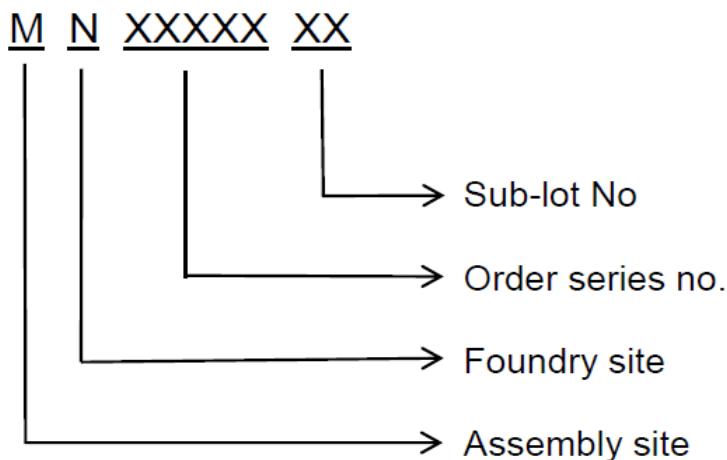


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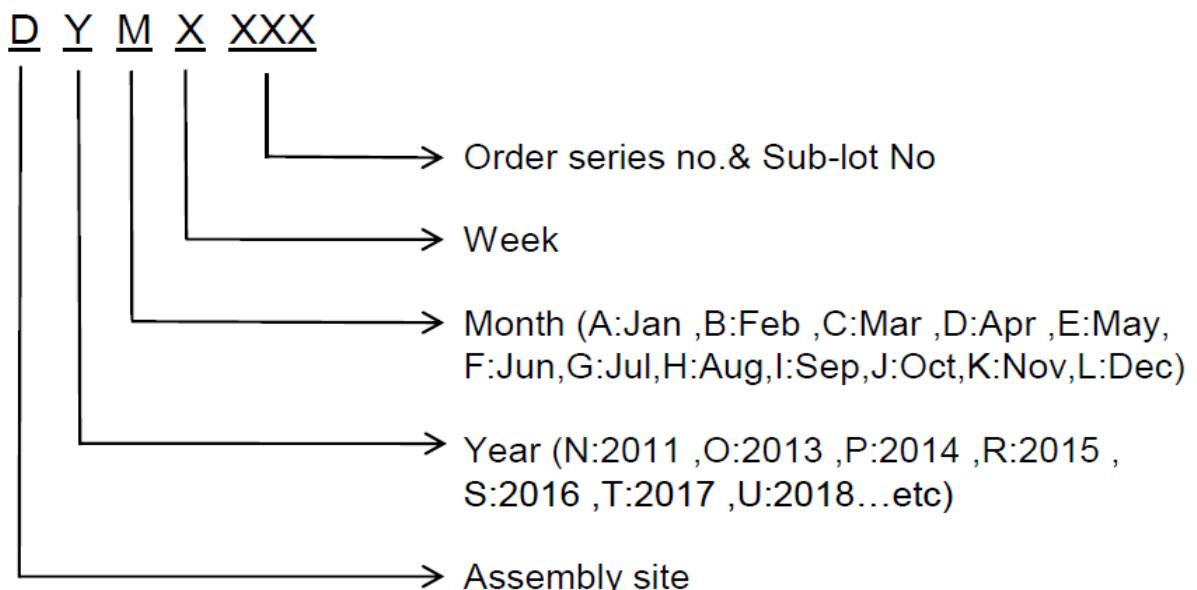
N-Channel Enhancement Mode MOSFET

C. Lot No.&Date Code rule

1. Lot No.



2. Date Code



PB210BM

N-Channel Enhancement Mode MOSFET

D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm		
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)		
3	U-NIKC	Height: 4 mm		
4	Package	Height: 2 mm		
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12		
6	Device	Height: 3 mm (Max: 16 Digit)		
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot		
8	D/C	Height: 3 mm (Max: 7 Digit)		
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed		
10	RoHS label	RoHS long axis: 12 mm minor axis: 6 mm bottom color: White Font color: Black Font style: Arial		
11	Halogen Free label	G Diameter: 10 mm bottom color: Green Font color: Black Font style: Arial		
12	Scan information	Device / Lot / D/C / QTY , Insert “ / ” between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least		